



Customer Information Notification

201603016I

Issue Date: 29-Mar-2016
Effective Date: 27-Jun-2016

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QUALITY

Management Summary

LPC178X_7X data sheet updates for dynamic external memory interface timing.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input checked="" type="checkbox"/> Electrical spec./Test coverage

LPC178x/7x data sheet update to Rev 5.4.

Information Notification

The data sheet for the LPC178X_7X has been updated to Rev. 5.4.

The following updates are provided:

- Added Table 18 "Dynamic characteristics: Dynamic external memory interface, read strategy bits (RD bits) = 00" for 10 pF load.
- Updated Table 19 "Dynamic characteristics: Dynamic external memory interface, read strategy bits (RD bits) = 00" for 30 pF load.
- Added Table 20 "Dynamic characteristics: Dynamic external memory interface, read strategy bits (RD bits) = 01" for 10 pF load.
- Updated Table 21 "Dynamic characteristics: Dynamic external memory interface, read strategy bits (RD bits) = 01" for 30 pF load.
- Updated Table 22 "Dynamic characteristics: Dynamic external memory interface programmable clock delays (CMDDLY, FBCLKDLY, CLKOUT0DLY and CLKOUT1DLY)".

Updates to Tables 19, 21, and 22, include corrected formulas to calculate timing values.

The revised data sheet is available on the NXP website.

There is no change to the product.

Why do we issue this Information Notification

For clarification of data sheet parameters.

Identification of Affected Products

Product identification does not change

Impact

Although no changes have been made to the product, customers should evaluate their applications if an external memory interface is used to interface SDRAM.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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